Title: Datasheet for LP8860-Q1 Customer Contact: PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Manager PCN Mare Bump Site PCN Mare Bump Material PCN Mare Fab Site PCN Mare Fab Materials	PCN Number: 20160121000		21000			PCN Date:		2/1/2016	
Assembly Process	Title: Datasheet	for LP8860-	Q1						
Assembly Site			ger		Dept:		Quality Services		
Assembly Process Data Sheet Wafer Bump Material Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Wafer Site Wafer Site Wafer Site Wafer Site Wafer Site Wafer Fab Site Wafer Site Wafer Site Wafer Site Wafer Site Wafer Fab Site Wafer Si	Change Type:					_		-	
Assembly Process	Assembly Site			Design		Wafer	Bum	p Site	
Mechanical Specification				Data Sheet		_			
Packing/Shipping/Labeling				Part number change		Wafer	Bump Process		
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: Texas Texas Texas Texas Texas Texas Texas LP8860-Q1 WWW.H.com SNVSA21C - MAY 2014 - REVISED DECEMBER 2015 Changes from Revision B (March 2015) to Revision C Page Added Features bullets re: Automotive Added Features bullets re: Automotive Changed "safely" to "Up to 48V" in Simplified Schematic Added EEPROM values for LP8860C in "Default EEPROM Context" table Changed wording of sentence beginning "MISO output" (4th sentence in SPI Interface section) Changed SPI Write Cycle and SPI Read Cycle diagrams Device Family Change From: Change To: LP8860-Q1 SNVSA21B SNVSA21C These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/lp8860-q1 Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected: LP8860AQVFPRQ1 LP8860CQVFPRQ1 LP8860EQVFPRQ1 LP8860EQVFPRQ1				Test Site		Wafer	Fab Site		
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail			
USA	PCNAmericasContact@list.ti.com			
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